

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KP-1608VGC-A	Green (InGaN)	WATER CLEAR	50	180	120°

Notes:

1. $\theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Green	520		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Green	525		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Green	35		nm	I _F =20mA
C	Capacitance	Green	100		pF	V _F =0V; f=1MHz
V _F [2]	Forward Voltage	Green	3.2	4	V	I _F =20mA
I _R	Reverse Current	Green		10	uA	V _R =5V

Notes:

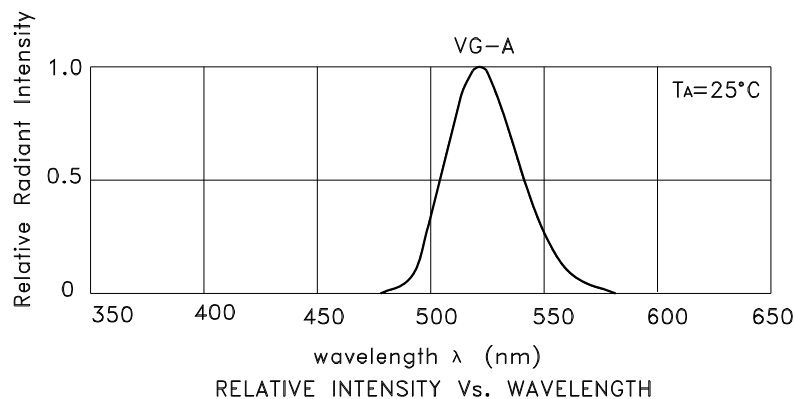
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units
Power dissipation	120	mW
DC Forward Current	30	mA
Peak Forward Current [1]	100	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

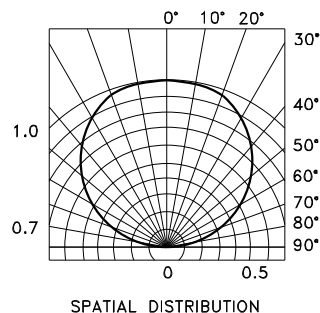
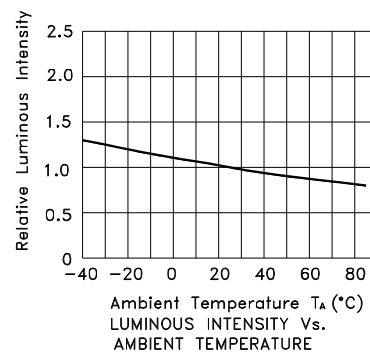
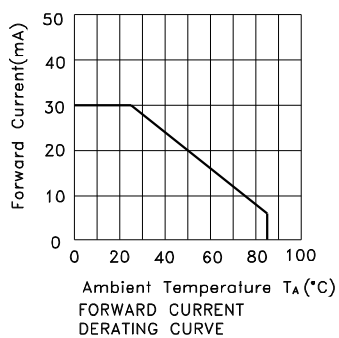
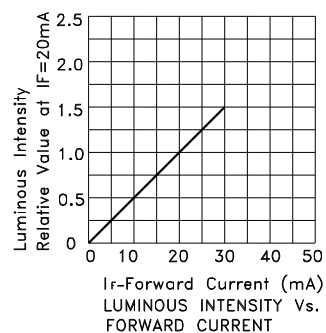
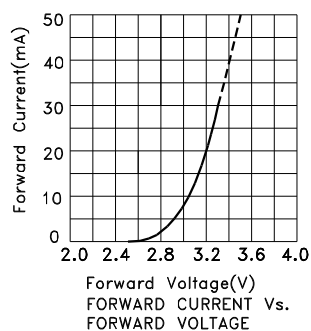
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



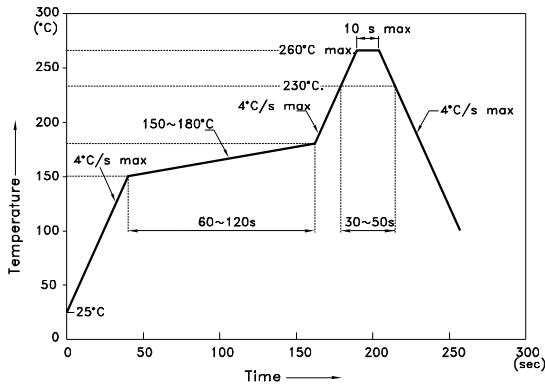
Green

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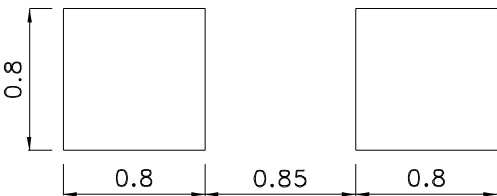
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Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Tape Specifications (Units : mm)

